



SamHop Microelectronics Corp.

STF8220

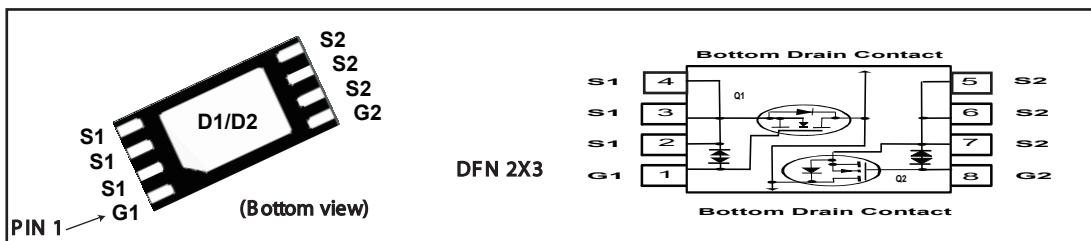
Oct.23 2006 ver1.1

Dual N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
V _{DSS}	I _D	R _{DS(ON)} (mΩ) Max
20V	7A	20 @ V _{GS} = 4.0V
		28 @ V _{GS} = 2.5V

FEATURES

- Super high dense cell design for low R_{DS(ON)}.
- Rugged and reliable.
- Surface Mount Package.
- ESD Protected.



ABSOLUTE MAXIMUM RATINGS (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Drain Current-Continuous @ T _J =25 °C -Pulsed ^b	I _D	7	A
	I _{DM}	30	A
Drain-Source Diode Forward Current ^a	I _S	1.7	A
Maximum Power Dissipation ^a	P _D	1.56	W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient ^a	R _{θJA}	80	°C/W
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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16V, V_{GS} = 0V$			1	μA
Gate-Body Leakage	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$			± 10	μA
ON CHARACTERISTICS^b						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.5	0.8	1.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS} = 4.0V, I_D = 7A$		17.5	20	m ohm
		$V_{GS} = 2.5V, I_D = 4A$		21	28	m ohm
Forward Transconductance	g_{FS}	$V_{DS} = 5V, I_D = 4A$		12		S
DYNAMIC CHARACTERISTICS^c						
Input Capacitance	C_{iss}	$V_{DS} = 10V, V_{GS} = 0V$ $f = 1.0MHz$		670		pF
Output Capacitance	C_{oss}			188		pF
Reverse Transfer Capacitance	C_{rss}			140		pF
SWITCHING CHARACTERISTICS^c						
Turn-On Delay Time	$t_{D(ON)}$	$V_{DD} = 10V,$ $I_D = 1A,$ $V_{GEN} = 4.0V,$ $R_{GEN} = 6\text{ ohm}$		15		ns
Rise Time	t_r			32		ns
Turn-Off Delay Time	$t_{D(OFF)}$			50		ns
Fall Time	t_f			30		ns
Total Gate Charge	Q_g	$V_{DS} = 10V, I_D = 4A,$ $V_{GS} = 4.0V$		10		nC
Gate-Source Charge	Q_{gs}			1.4		nC
Gate-Drain Charge	Q_{gd}			4.2		nC

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ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS ^b						
Diode Forward Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_S = 1.7 \text{ A}$			0.8	1.2

Notes

a.Surface Mounted on FR4 Board, $t \leq 10 \text{ sec}$.

b.Pulse Test Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.

c.Guaranteed by design, not subject to production testing.

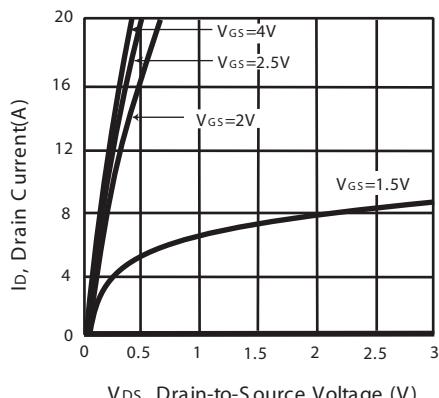


Figure 1. Output Characteristics

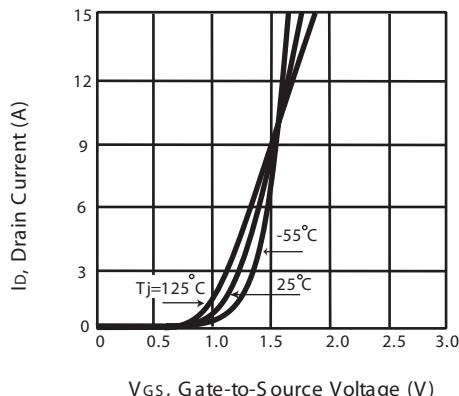


Figure 2. Transfer Characteristics

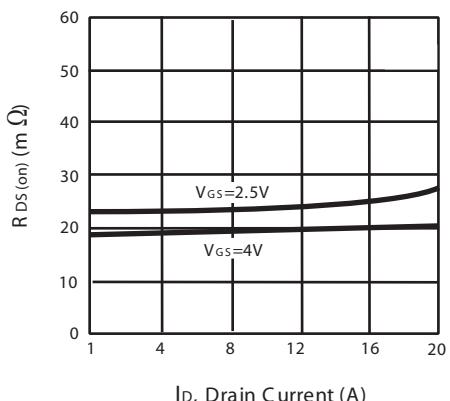


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

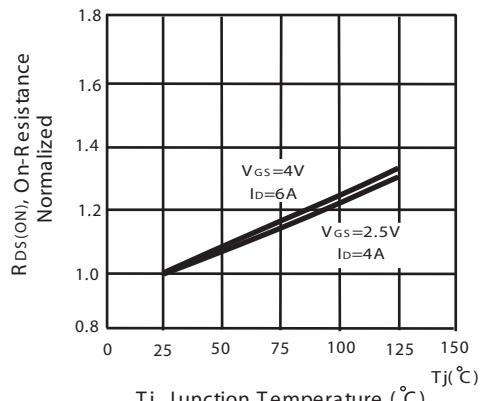


Figure 4. On-Resistance Variation with Drain Current and Temperature

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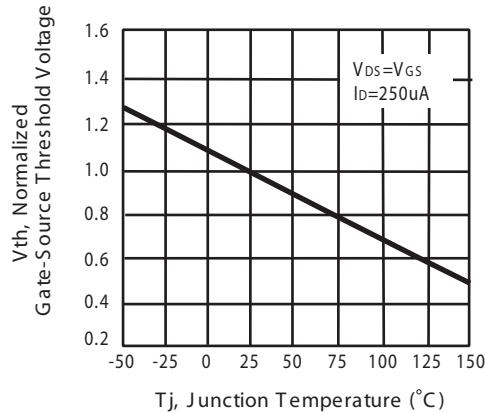


Figure 5. Gate Threshold Variation with Temperature

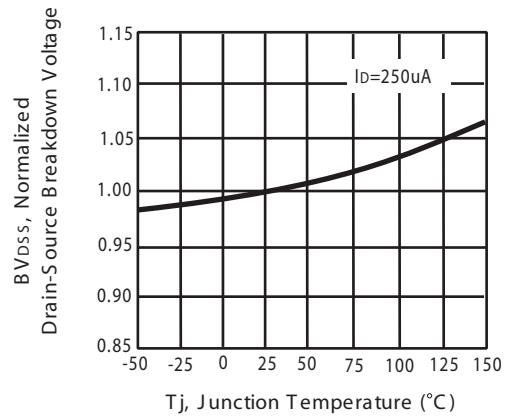


Figure 6. Breakdown Voltage Variation with Temperature

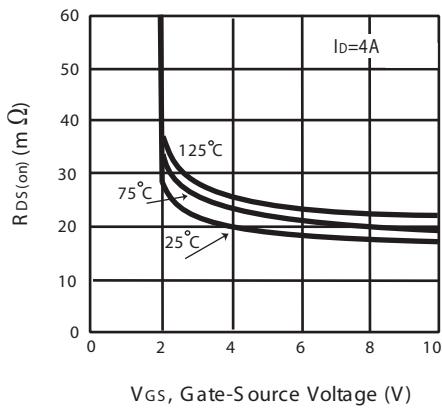


Figure 7. On-Resistance vs. Gate-Source Voltage

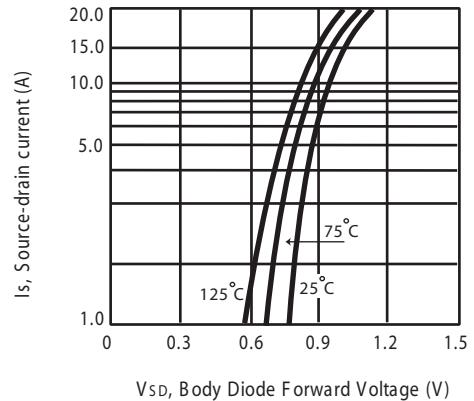


Figure 8. Body Diode Forward Voltage Variation with Source Current

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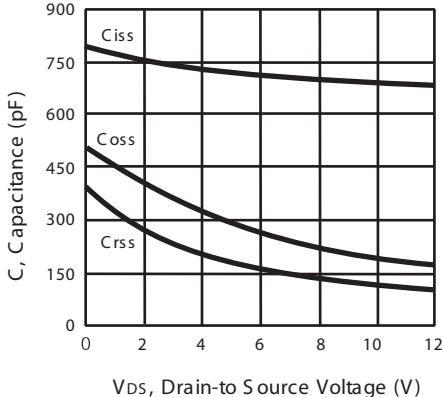


Figure 9. Capacitance

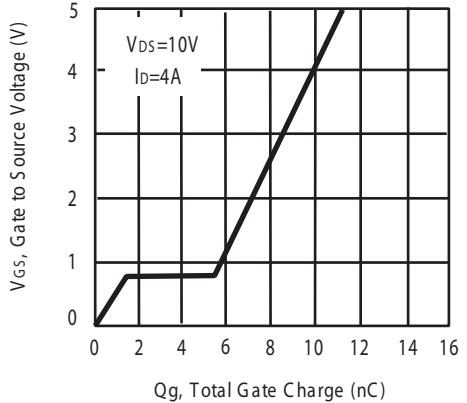


Figure 10. Gate Charge

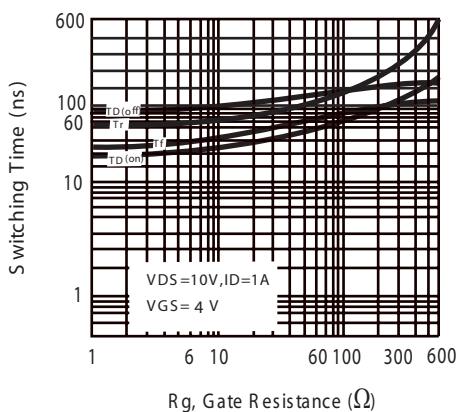


Figure 11. switching characteristics

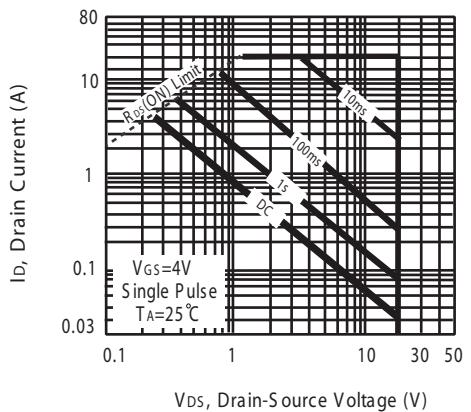


Figure 12. Maximum Safe Operating Area

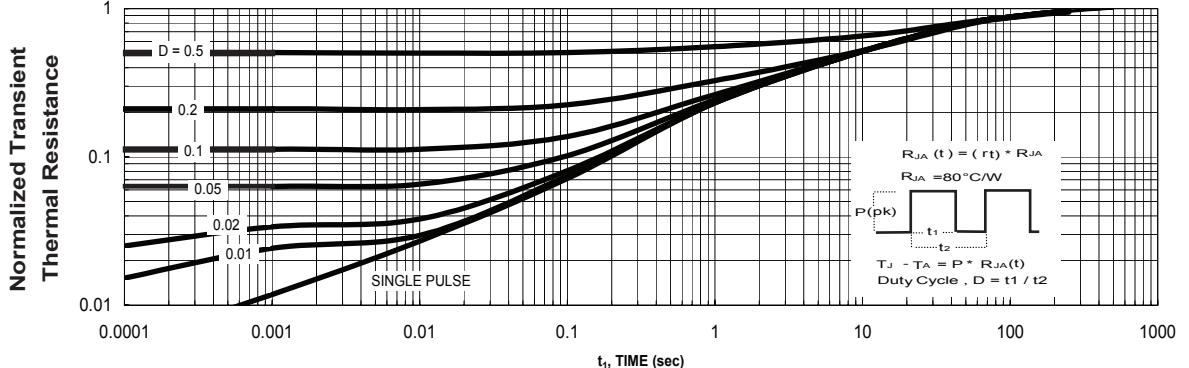
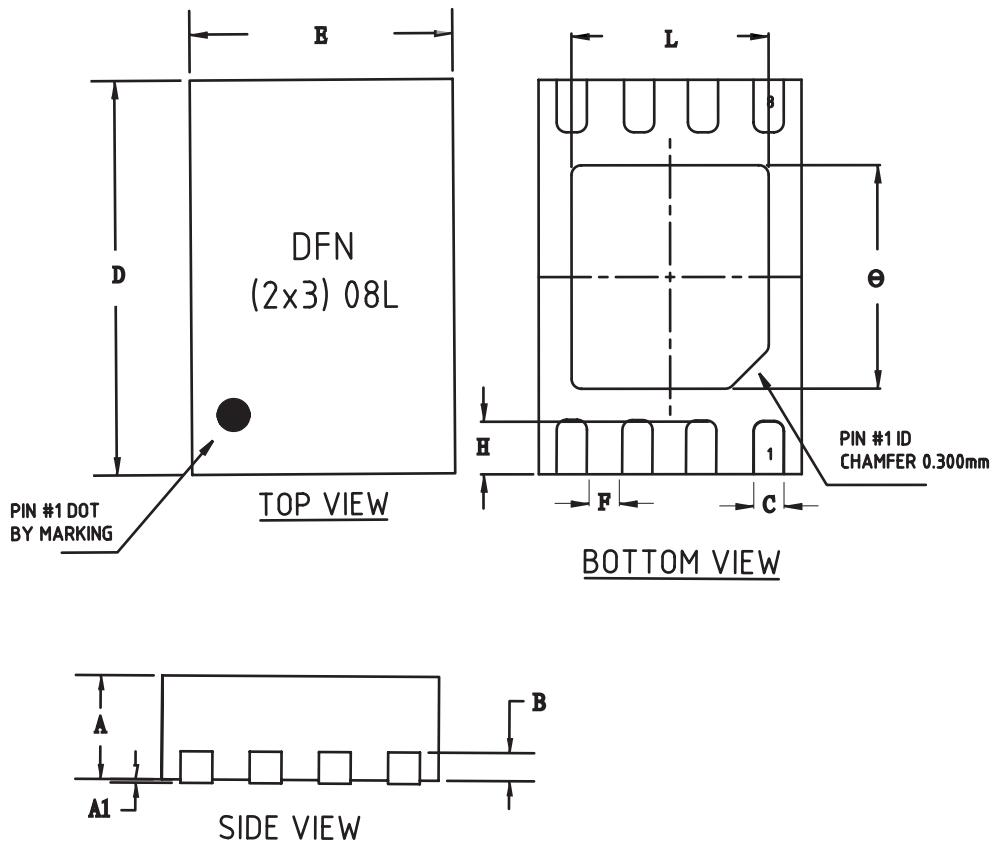


Figure 13. Square Wave Pulse Duration(sec)
Normalized Thermal Transient Impedance Curve

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PACKAGE OUTLINE DIMENSIONS

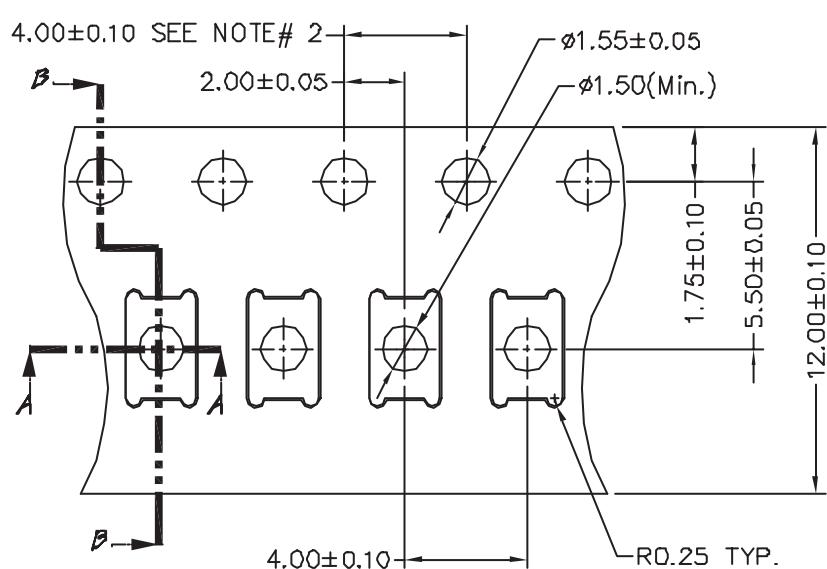
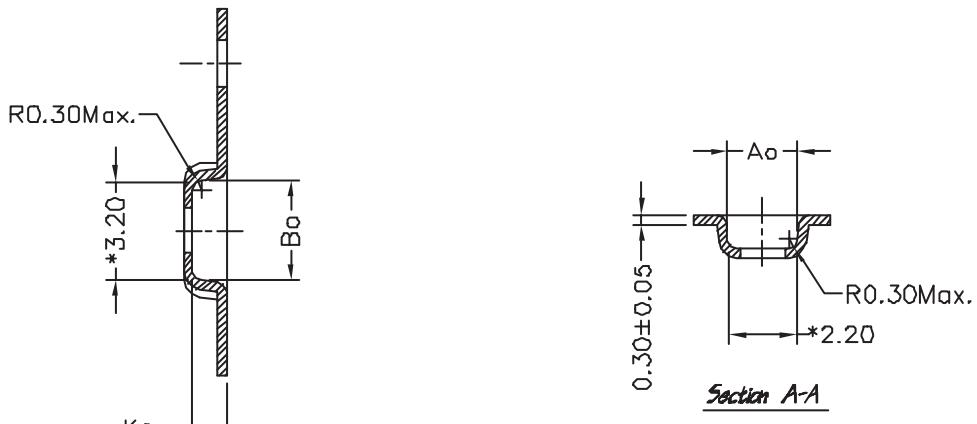
DFN



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.80	1.00	0.031	0.039
A1	0.00	0.025	0.00	0.001
D	2.95	3.05	0.116	0.120
E	1.95	2.05	0.077	0.081
H	0.30	0.45	0.014	0.018
L	1.45	1.55	0.057	0.061
e	1.65	1.75	0.065	0.069
B	0.195	0.211	0.0076	0.008
C	0.18	0.28	0.007	0.011
F	0.22	0.32	0.008	0.126

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DFN Tape and Reel Data



DIM.	mm
Ao	2.30
Bo	3.30
Ko	1.10